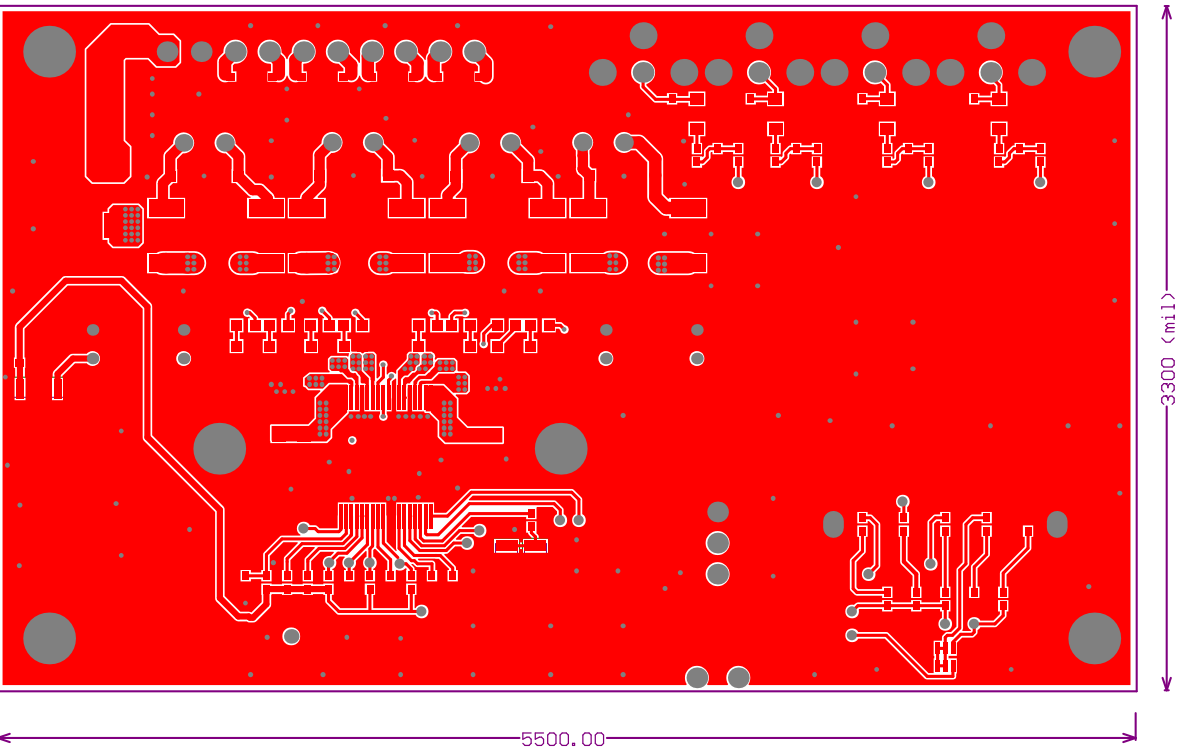


Title		
TAS514BDKD EVB Schematic		
Size	Number	Revision
B		
Date:	3/14/2012	Sheet of
File:	C:\Documents and Settings\Sheet1.SchDoc	Drawn By:



### Fab Notes

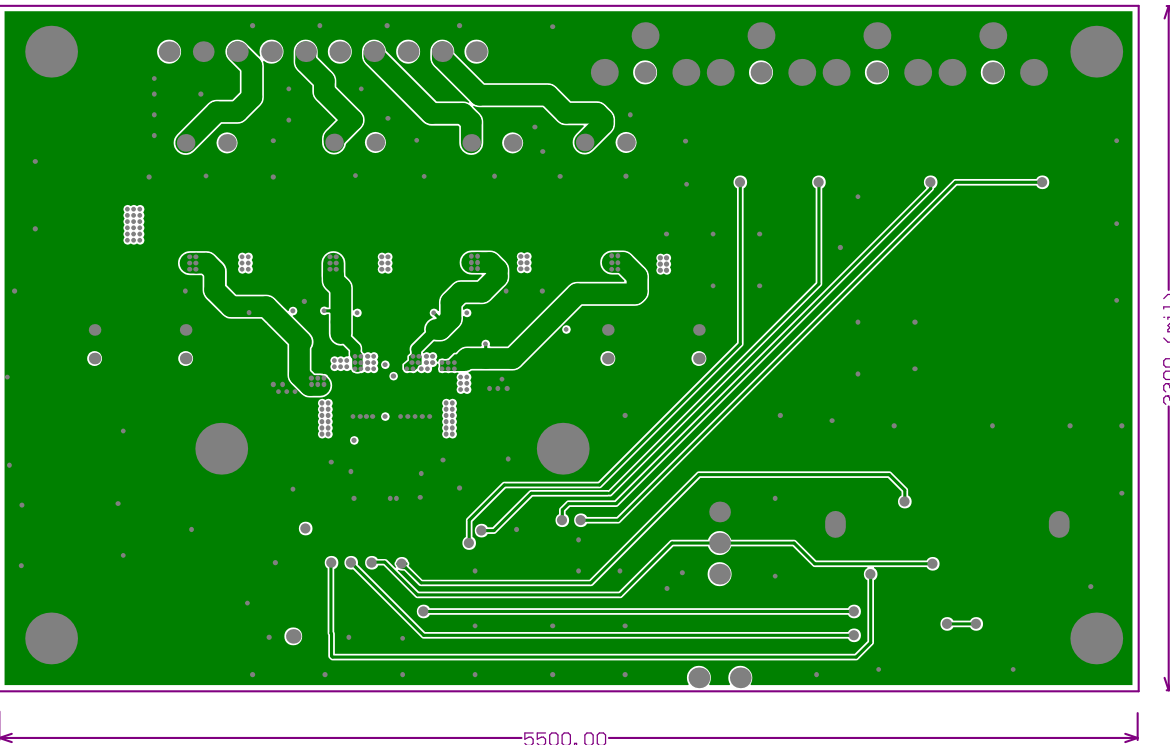
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Hole Diameters:   <=0.080 +/-0.003  
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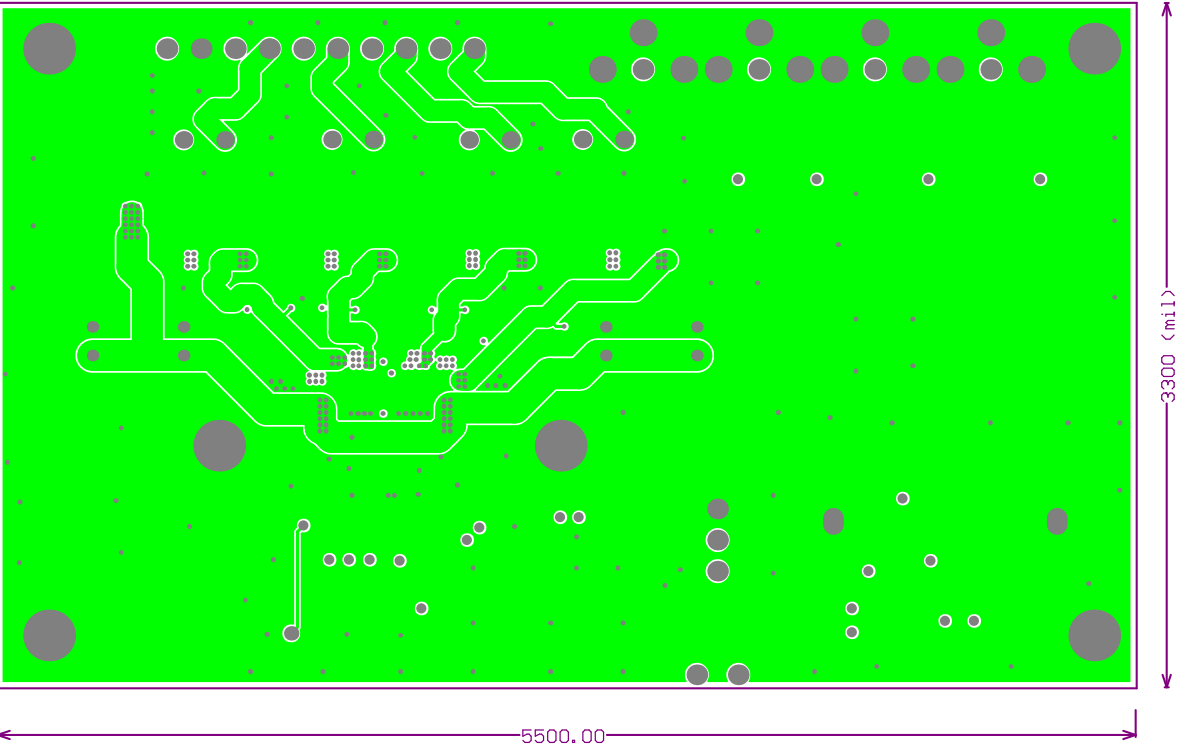
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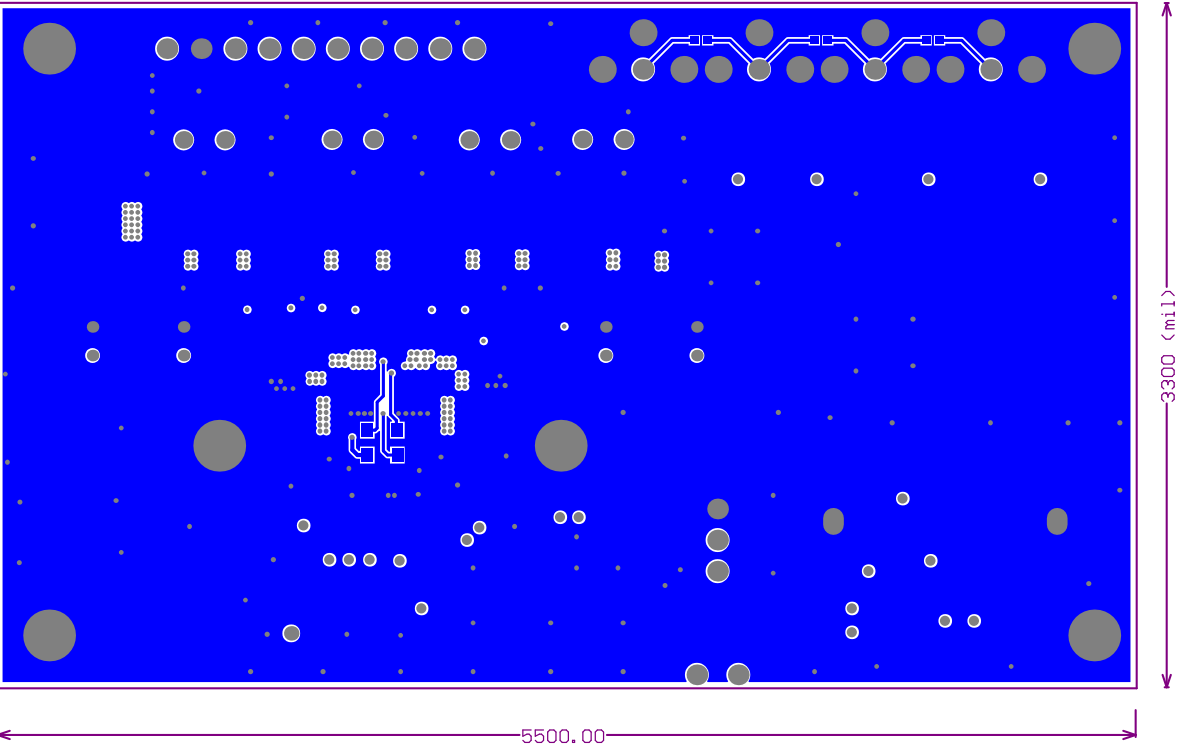
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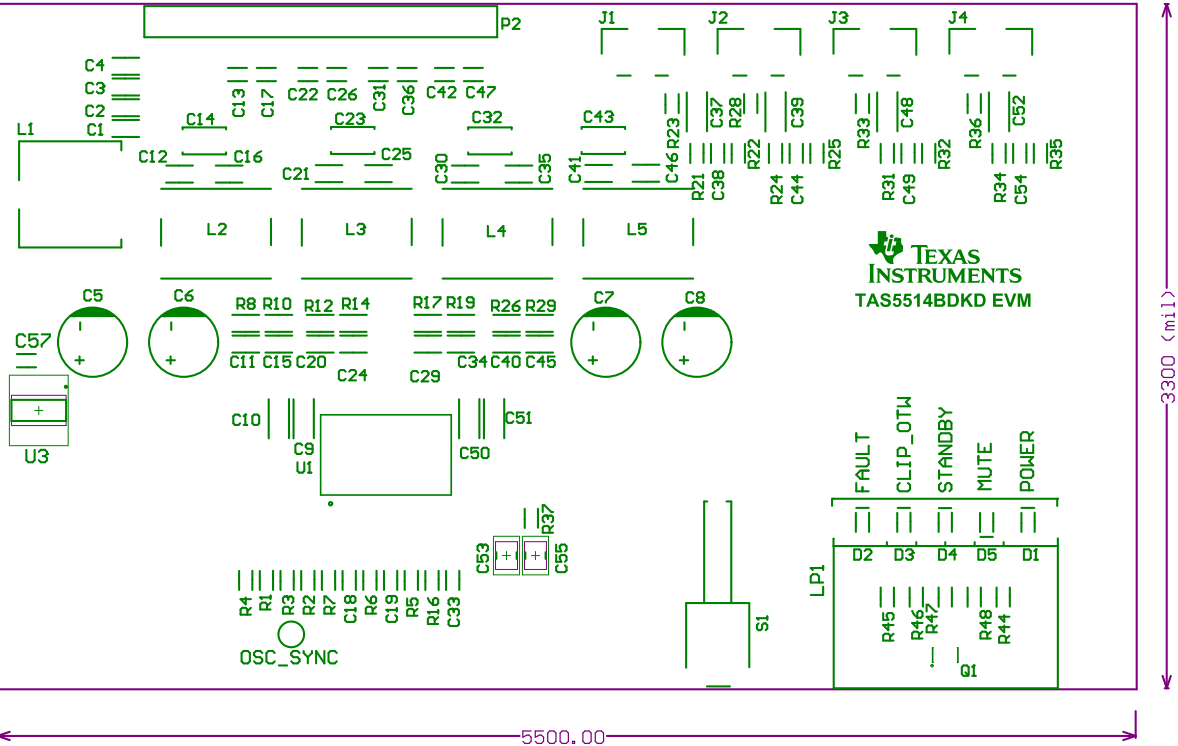
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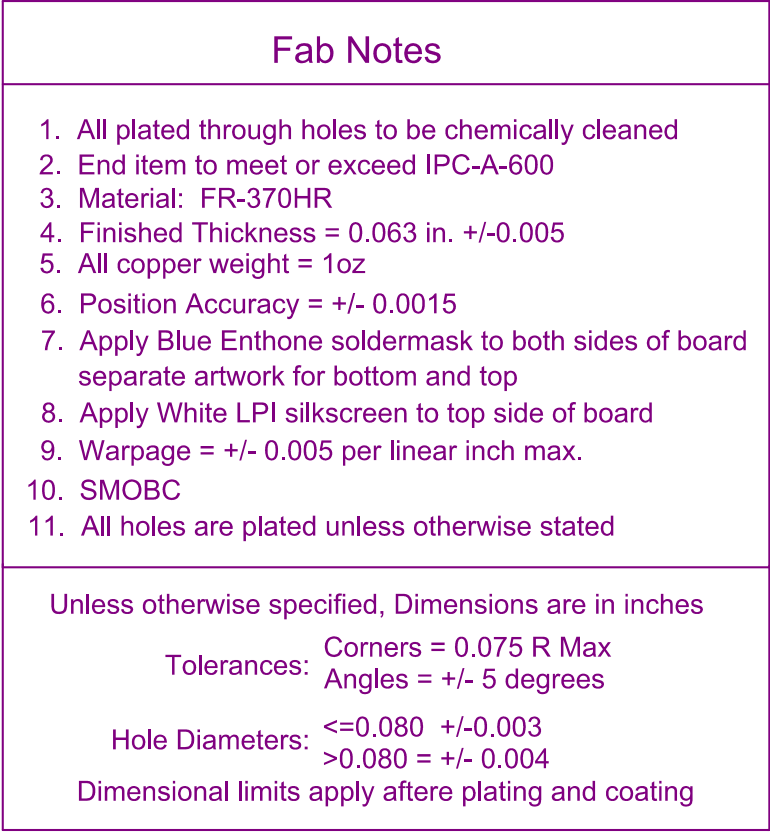
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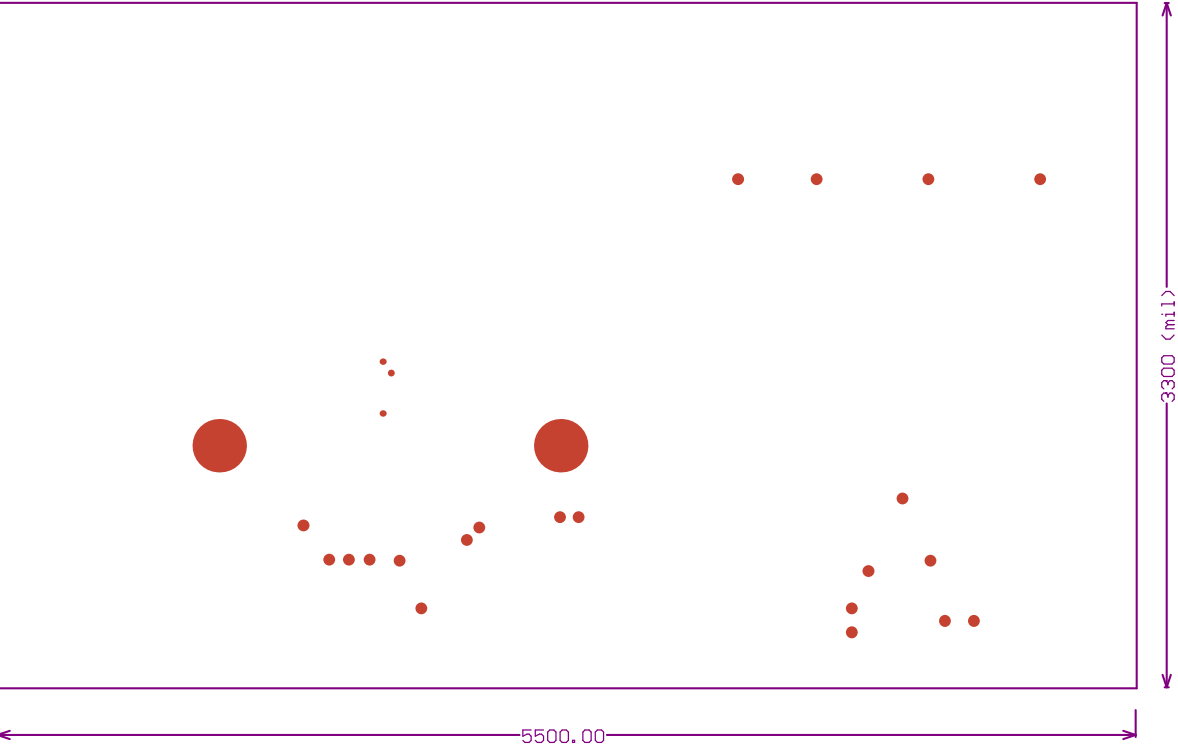
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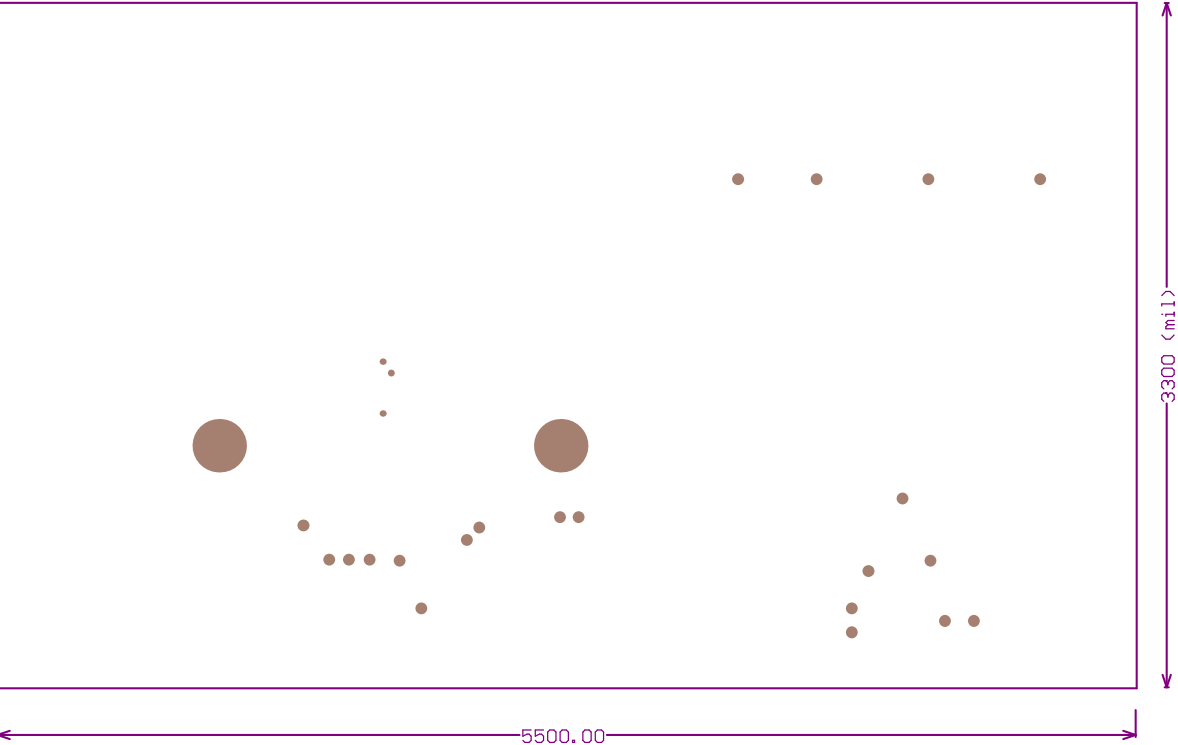
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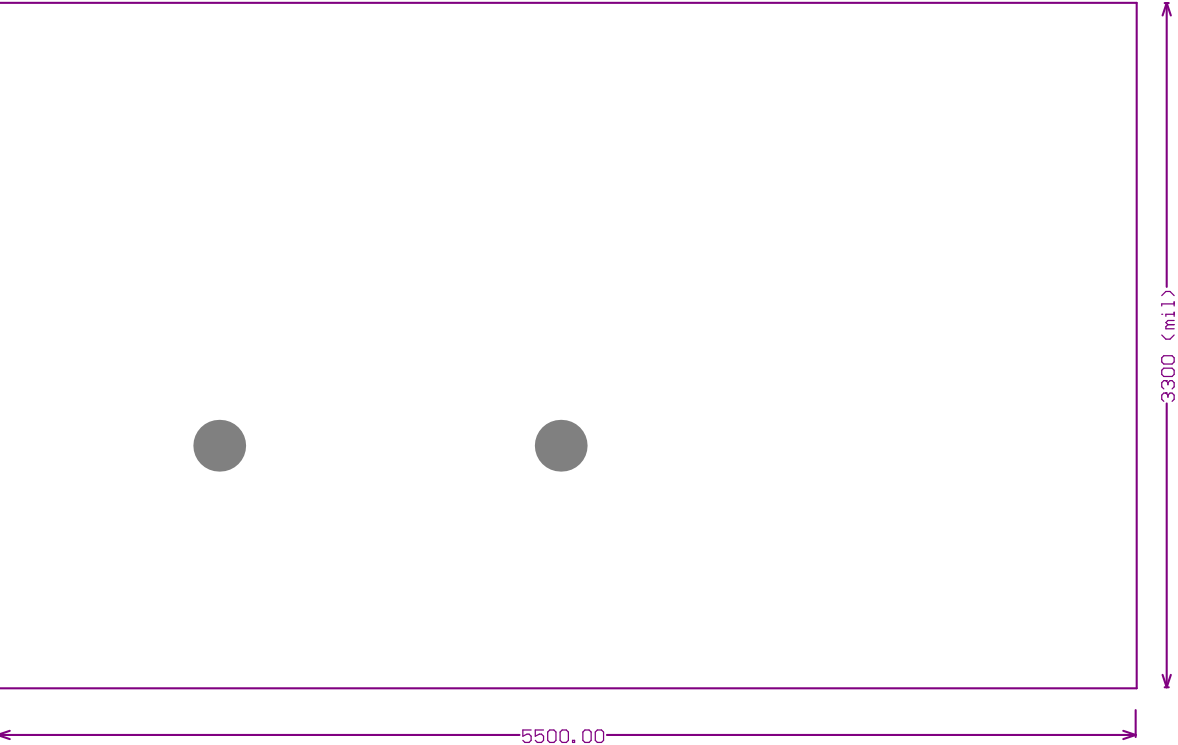
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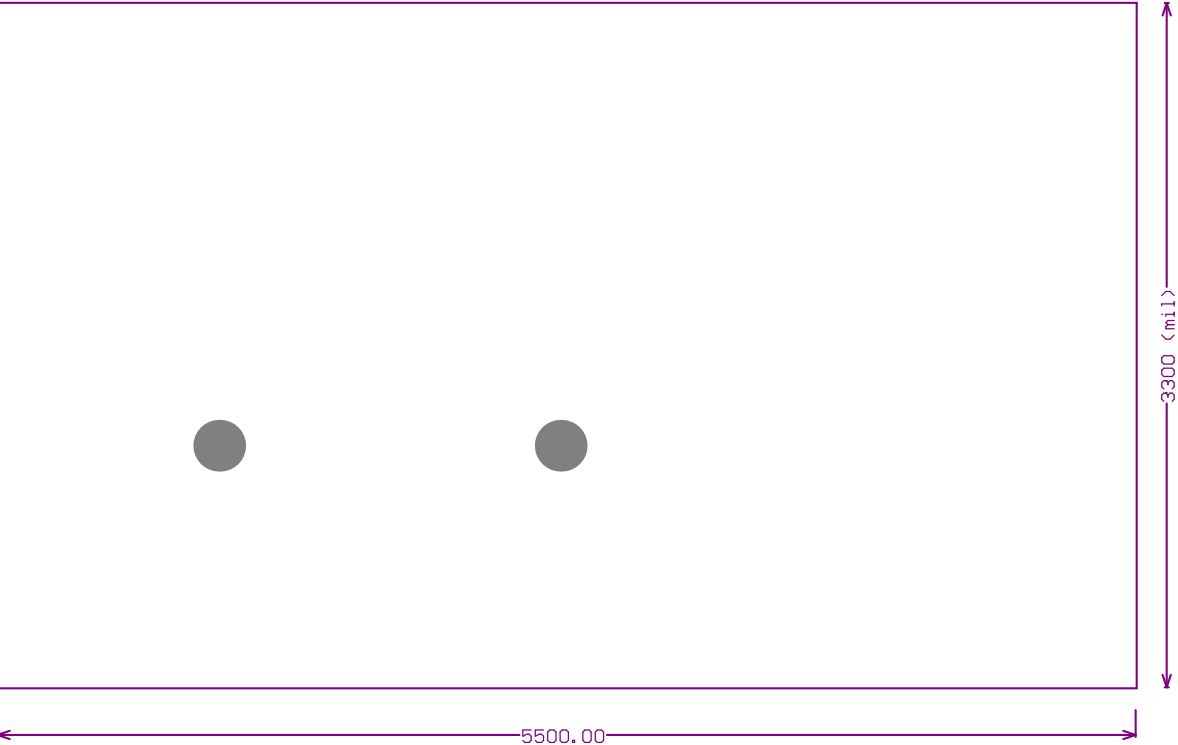
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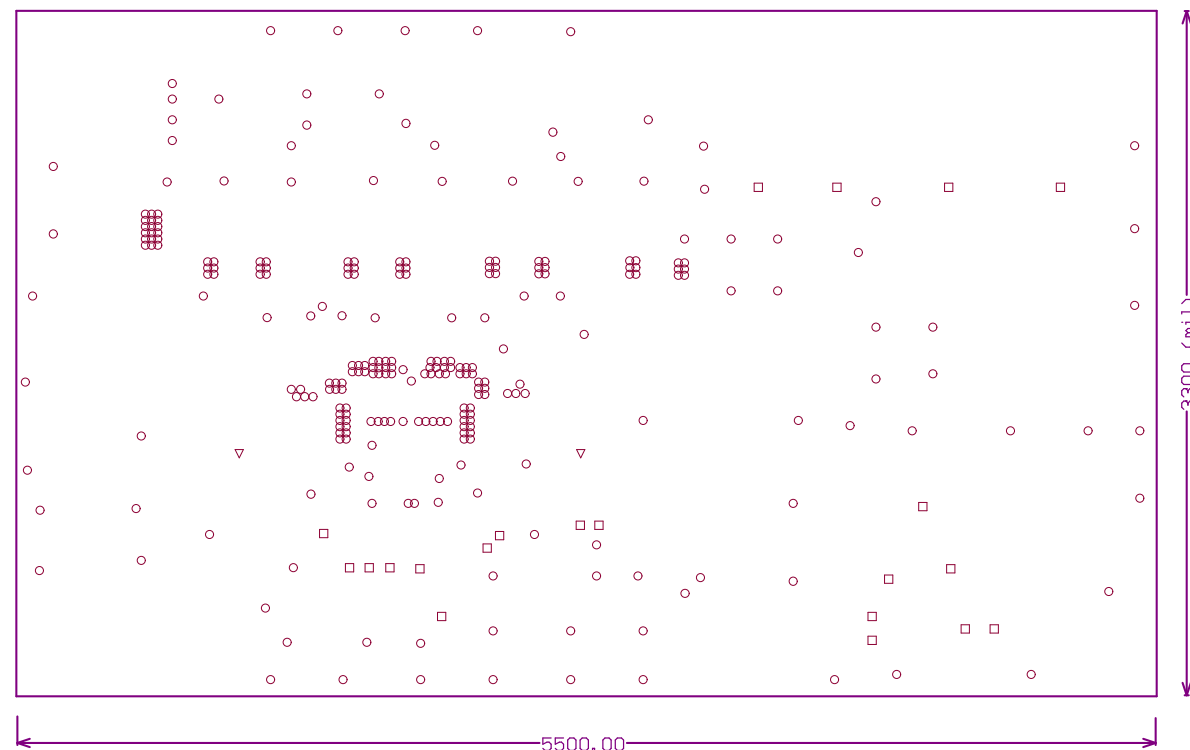
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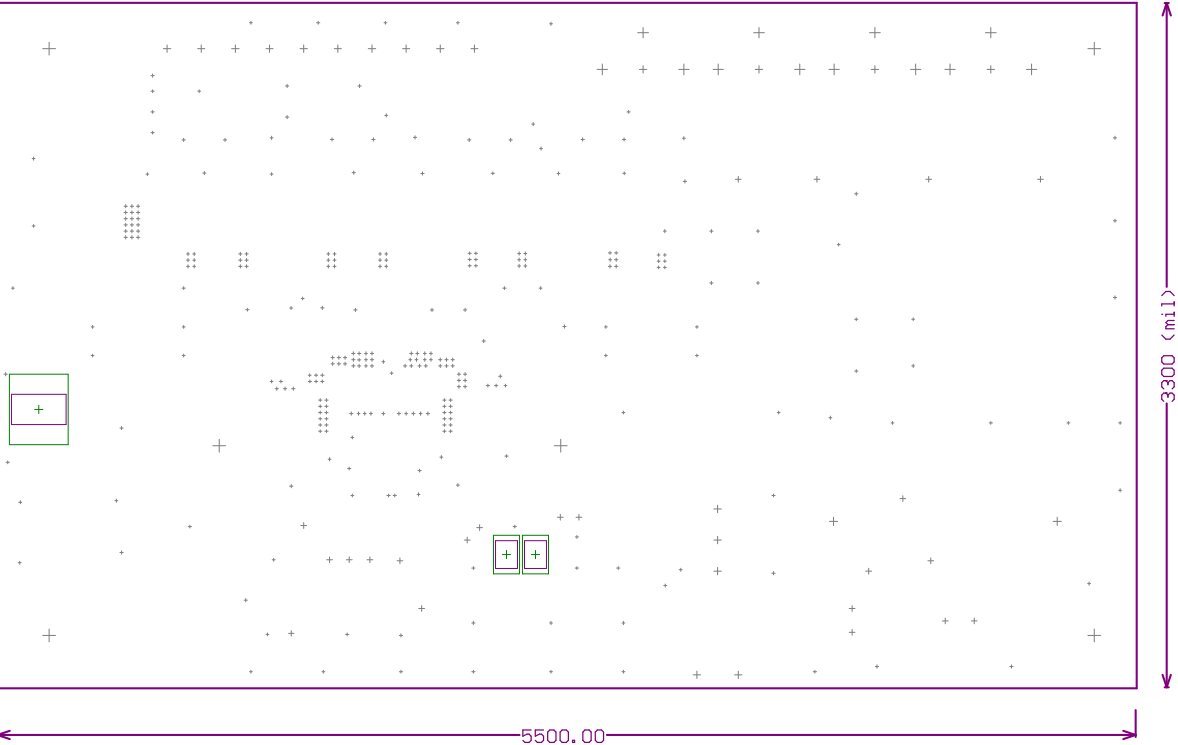
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